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(54) Title: ELECTROMECHANICAL SWITCHING DEVICE PACKAGE WITH CONTROLLED IMPEDANCE ENVIRONMENT

(57) Abstract

A reed switch package (100) is disclosed that includes a reed switch (111) with at least one electrical signal path (106). A cylindrical ground shield (110) is provided about the reed switch (111). Ground terminals (108) are connected to opposing sides of the ground shield (110) so that the ground terminals (108) are on opposing sides of the signal terminal (106) and lie in the same plane. The reed switch (111) resides on a support substrate (222). An electrically conductive signal via (134) extends through the main body (212) and connects to the signal terminal (106). Ground vias (134) extend through the main body (212) and respectively connect to the ground terminals (108). The ground vias (134) are on opposing sides of the signal via (134) and lie in the same plane as the signal via (114). The signal and ground vias (134) exit at the bottom of the main body (212) and are connected to a circuit via solder balls (224) to provide a compact surface mount package with a controlled impedance environment.

